25C828, 25C828A

Silicon NPN Epitaxial Planar Type

For small-signal amplification

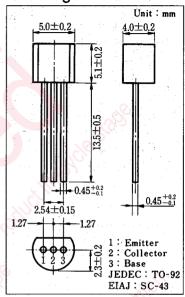
■ Features

•Large DC current gain hFE

■ Absolute Maximum Ratings (Ta=25°C)

Item		Symbol	Value	Unit	
Collector-Base Voltage	2SC828	37	30	*77	
	2SC828A	V _{cвo}	45	V	
Collector-Emitter Voltage	2SC828	37	25	T.	
	2SC828A	V_{ceo}	45	V	
Emitter-Base Voltage		V _{EBO}	7	V	
Peak Collector Voltage		I _{CP}	. 100	mA	
Collector Current		I_c	50	mA	
Collector Power Dissipation		P _c	400	mW	
Junction Temperature		Ti	150	c	
Storage Temperature		T _{stg}	−55~ +150	C C	
				70. 07	

■ Package Dimensions

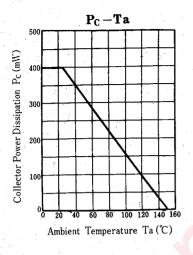


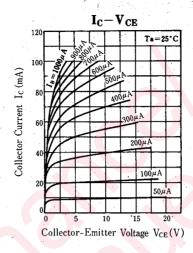
■ Electrical Characteristics (Ta=25°C)

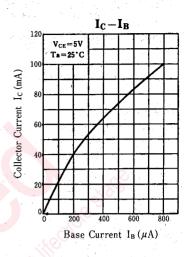
Iter	n	Symbol	Condition	min.	typ.	max.	Unit
Collector-Base 2SC828		V J	$I_{c} = 10 \ \mu A, I_{F} = 0$	30	1	5	v
Voltage	2SC828A	V _{cво}	$I_c = 10 \mu A$, $I_E = 0$	45	60/		V
Collector-Emitter	2SC828	V_{CEO} $I_C = 2 \text{ mA}, I_B = 0$	I -2 m A I -0	25	0		V
Voltage	2SC828A		$I_C = 2 \text{ mA}, I_B = 0$	45			
Emitter-Base Voltage		V _{EBO}	$I_{\rm E} = 10 \ \mu {\rm A}, I_{\rm C} = 0$	7			V
DC Current Gain		h _{FE} *	$V_{CE}=5 \text{ V}, I_{C}=2 \text{ mA}$	130		520	
Base-Emitter Voltage		V _{BE}	$V_{CB} = 5 \text{ V}, I_{C} = 10 \text{ mA}$. 0.8	V V
Collector-Emitter Saturation Voltage		V _{CE(sat)}	$I_c = 50 \text{ mA}, I_B = 5 \text{ mA}$		0.14	,	· V
Transition Frequency f		f _T	$V_{CB}=10V, I_{E}=-2mA, f=200MHz$		220		MHz
Noise Figure		NF	$V_{CE}=5 \text{ V}, I_{C}=0.2 \text{ mA}, R_{g}=2 \text{ k}\Omega, f=1 \text{ kHz}$		6		dB

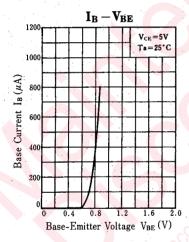
*hFE Ranking

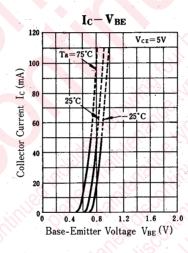
Rank	Q	R	S
hre	130~260	180~360	260~520

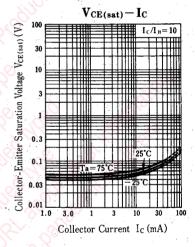


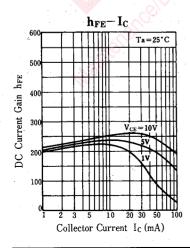


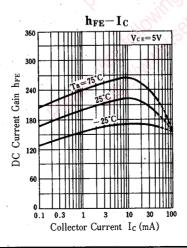


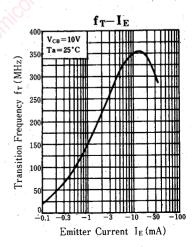


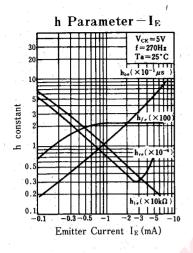


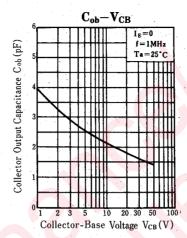


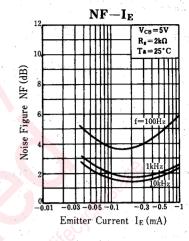












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